

	Type	Hits	Search Text
1	BRS	24	(die adj pad) and PCB and wiring
2	IS&R	17	((("5280192") or ("5579207") or ("6072233") or ("6180881") or ("5872025") or ("6093029") or ("5963430") or ("6313522"))).PN.
3	BRS	0	(metal adj peg) and (printed adj circuit adj line)
4	BRS	111	metal adj peg
5	BRS	1	(metal adj peg) and packaging
6	BRS	7	(metal adj peg) and (die chip)
7	BRS	210	257/697.ccls. and wiring
8	BRS	4317	(chip die) and wiring and ball
9	BRS	46	((chip die) and wiring and ball) and (circuit adj line)
10	IS&R	9	((("6201292") or ("6247229") or ("6025640") or ("6281047"))).PN.
11	IS&R	4	((("6069396") or ("6232636"))).PN.
12	IS&R	8	((("6229205") or ("6204090") or ("5965947") or ("6157074"))).PN.
13	BRS	970	line adj mask
14	BRS	0	(line adj mask) and (insulating adj paint)
15	BRS	0	(line adj mask) and paint and trace
16	BRS	455	(line adj mask) and circuit

	Type	Hits	Search Text
17	BRS	10	((line adj mask) and circuit) and (screen adj printing)
18	BRS	22	mask near5 paint and thermally
19	BRS	974	257/718-720.ccls. and (heat adj sink)
20	BRS	3	257/718-720.ccls. and (heat adj sink) and (die adj pad)
21	BRS	41	(257/718-720.ccls. and (heat adj sink)) and encapsulant
22	IS&R	3	("5291062").PN.
23	BRS	329	(bond adj pad) and (heat adj sink)
24	BRS	189	(bond adj pad) and (heat adj sink) and 257/\$
25	BRS	78	257/697,711,737-738,666.ccls. and (wiring adj connect\$4)
26	BRS	70	438/15,106,112,121,124,612.ccls. and (metal adj substrate)
27	BRS	15	438/613.ccls. and (metal adj substrate)
28	BRS	1033	line adj mask
29	BRS	503	(line adj mask) and circuit
30	BRS	54	((chip die IC) and wiring and ball) and (circuit adj line)
31	BRS	1425	(metal adj substrate) and (peg pin)

	Type	Hits	Search Text
32	BRS	146	((metal adj substrate) and (peg pin)) and 257/\$.ccls.

	Type	L #	Hits	Search Text	DBs
1	IS&R	L1	7	((("6025640") or ("6247229") or ("5807610"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
2	IS&R	L2	2	("6211462").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3	BRS	L3	28	(die adj pad) near1 small near1 die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4	BRS	L4	11	liu-wen-chun.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
5	BRS	L5	2	("5977633"   "6201292").PN.	USPAT
6	BRS	L6	6	lai-chien-hung.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7	BRS	L7	0	20020089053.URPN.	USPAT
8	BRS	L9	673	438/613,15,106.ccls. and (die IC chip) and wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
9	BRS	L8	2	438/613,15,106.ccls. and (die IC chip) and wiring and (trace adj line)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
10	BRS	L10	3	438/613,15,106.ccls. and (die IC chip) and wiring and (circuit adj line)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
11	BRS	L11	673	438/613,15,106.ccls. and (die IC chip) and wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
12	BRS	L12	237	438/112,121,124.ccls. and (die IC chip) and wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
13	BRS	L13	241	438/612.ccls. and (die IC chip) and wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
14	BRS	L14	1139	257/666,737-738.ccls. and (die IC chip) and wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
15	IS&R	L15	2	("6380062").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
16	BRS	L16	1	257/666,737-738.ccls. and (die IC chip) and wiring and (circuit adj line)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
17	BRS	L17	103	257/666,737-738.ccls. and (die IC chip) and wiring and trace	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	L #	Hits	Search Text	DBs
18	BRS	L18	45	257/697,711,678.ccls. and (die IC chip) and wiring and trace	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB